

**IN THE SPECIFICATION:**

The specification as amended below with replacement paragraphs shows added text with underlining and deleted text with ~~striketrough~~.

Please REPLACE paragraph [0017] as follows:

Reference numeral 22 is an electronic component mounted at the housing preform 20, while 24 is an interconnect for electrically connecting an electronic component 22. FIGS. 3A and 3B show an example of formation of the housing preform 20 mounting the electronic components 22. FIG. 3A shows the state of mounting electronic components 22 on a substrate 22\_26 and laminating the surface of the substrate 26 mounting the electronic components 22 by a protective film 28 made of a plastic, while FIG. 3B shows the state where electronic components 22 mounted on the substrate 26 are covered by the protective film 28 so as to be buried inside the protective film 28. The substrate 26 and the protective 28 both have pliability. The substrate 26 and the protective film 28 form a plate member housing the electronic components 22. Note that the protective film 28 is preferably made using a thermoplastic film.